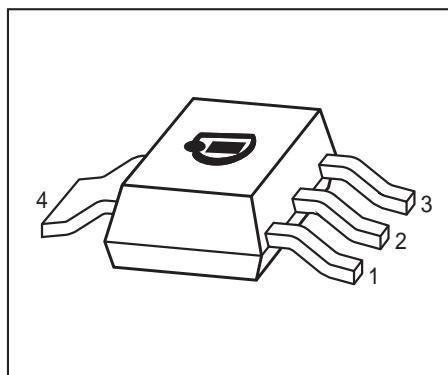


## NPN Silicon High-Voltage Transistors

- Suitable for video output stages TV sets and switching power supplies
- High breakdown voltage
- Low collector-emitter saturation voltage
- Complementary type: BFN39 (PNP)
- Pb-free (RoHS compliant) package<sup>1)</sup>
- Qualified according AEC Q101



Type	Marking	Pin Configuration						Package
BFN38	BFN38	1=B	2=C	3=E	4=C	-	-	SOT223

### Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	$V_{CEO}$	300	V
Collector-base voltage	$V_{CBO}$	300	
Emitter-base voltage	$V_{EBO}$	6	
Collector current	$I_C$	200	mA
Peak collector current	$I_{CM}$	500	
Base current	$I_B$	100	
Peak base current	$I_{BM}$	200	
Total power dissipation- $T_S \leq 124^\circ\text{C}$	$P_{tot}$	1.5	W
Junction temperature	$T_j$	150	$^\circ\text{C}$
Storage temperature	$T_{sta}$	-65 ... 150	

### Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point <sup>2)</sup>	$R_{thJS}$	$\leq 17$	K/W

<sup>1</sup>Pb-containing package may be available upon special request

<sup>2</sup>For calculation of  $R_{thJA}$  please refer to Application Note Thermal Resistance

**Electrical Characteristics** at  $T_A = 25^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>DC Characteristics</b>					
Collector-emitter breakdown voltage $I_C = 1 \text{ mA}, I_B = 0$	$V_{(\text{BR})\text{CEO}}$	300	-	-	V
Collector-base breakdown voltage $I_C = 100 \mu\text{A}, I_E = 0$	$V_{(\text{BR})\text{CBO}}$	300	-	-	
Emitter-base breakdown voltage $I_E = 100 \mu\text{A}, I_C = 0$	$V_{(\text{BR})\text{EBO}}$	6	-	-	
Collector-base cutoff current $V_{CB} = 250 \text{ V}, I_E = 0$ $V_{CB} = 250 \text{ V}, I_E = 0, T_A = 150^\circ\text{C}$	$I_{\text{CBO}}$	-	-	0.1 20	$\mu\text{A}$
Emitter-base cutoff current $V_{EB} = 5 \text{ V}, I_C = 0$	$I_{\text{EBO}}$	-	-	100	nA
DC current gain <sup>1)</sup> $I_C = 1 \text{ mA}, V_{CE} = 10 \text{ V}$ $I_C = 10 \text{ mA}, V_{CE} = 10 \text{ V}$ $I_C = 30 \text{ mA}, V_{CE} = 10 \text{ V}$	$h_{\text{FE}}$	25 40 30	-	-	-
Collector-emitter saturation voltage <sup>1)</sup> $I_C = 20 \text{ mA}, I_B = 2 \text{ mA}$	$V_{\text{CEsat}}$	-	-	0.5	V
Base emitter saturation voltage <sup>1)</sup> $I_C = 20 \text{ mA}, I_B = 2 \text{ mA}$	$V_{\text{BEsat}}$	-	-	0.9	

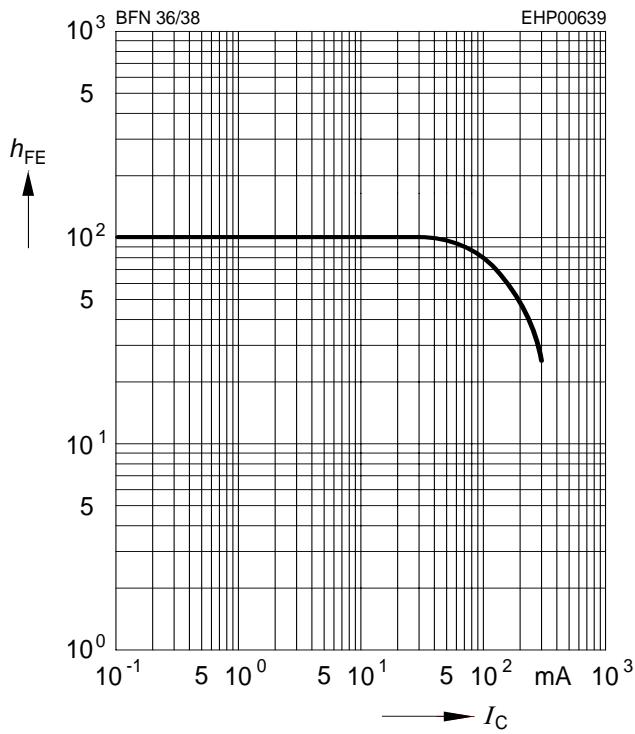
**AC Characteristics**

Transition frequency $I_C = 20 \text{ MHz}, V_{CE} = 10 \text{ V}, f = 20 \text{ MHz}$	$f_T$	-	70	-	MHz
Collector-base capacitance $V_{CB} = 30 \text{ V}, f = 1 \text{ MHz}$	$C_{\text{cb}}$	-	1.5	-	pF

<sup>1</sup>Pulse test:  $t < 300\mu\text{s}$ ;  $D < 2\%$

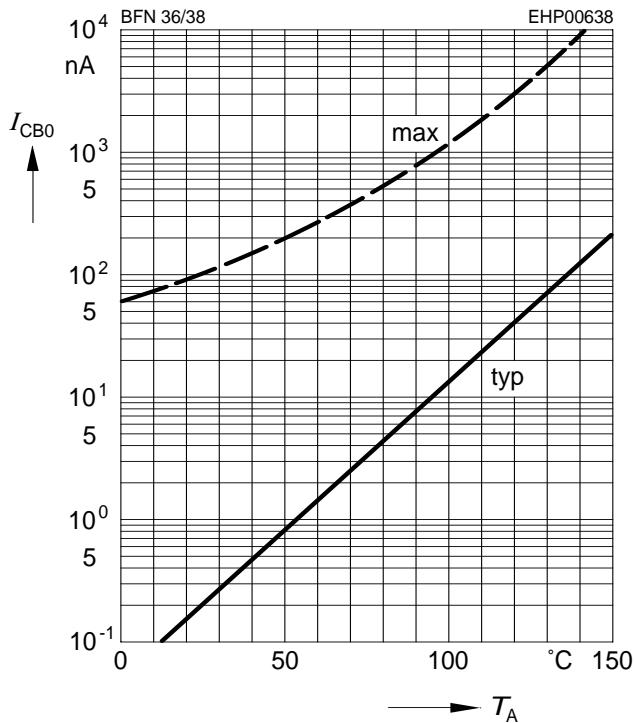
**DC current gain**  $h_{FE} = f(I_C)$

$V_{CE} = 10 \text{ V}$



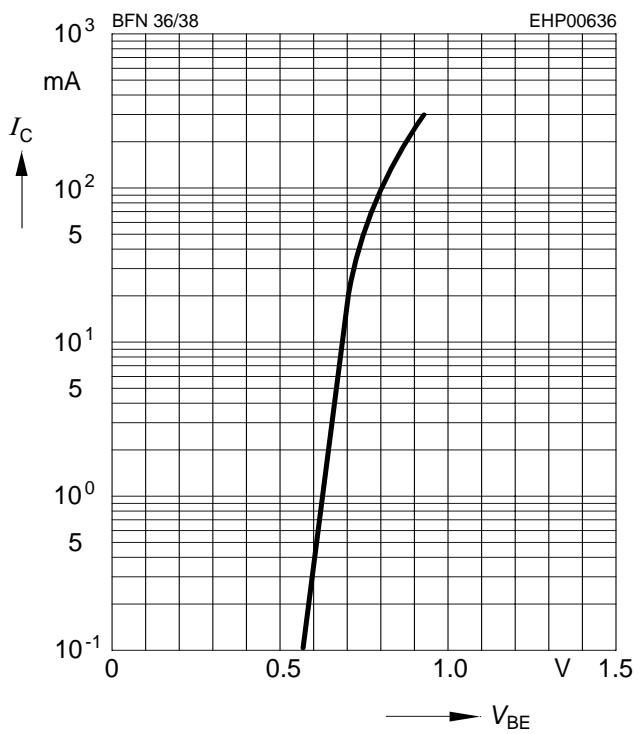
**Collector cutoff current**  $I_{CBO} = f(T_A)$

$V_{CB} = 30 \text{ V}$



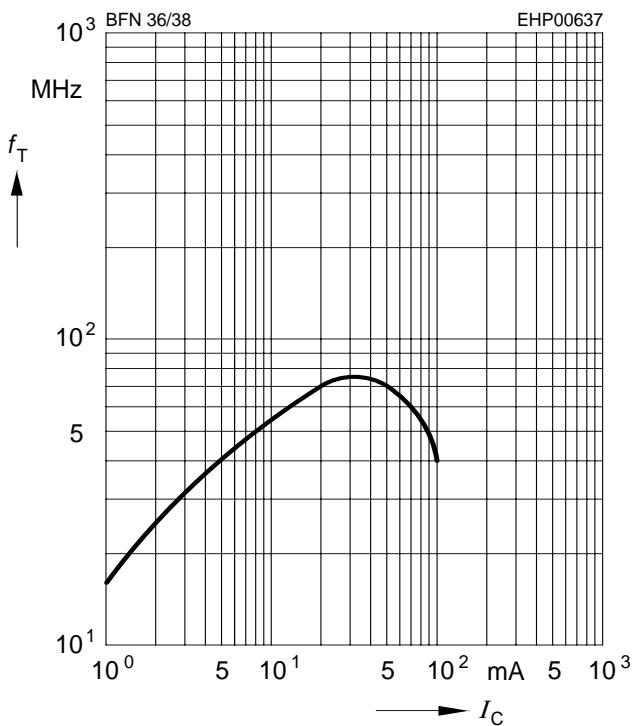
**Collector current**  $I_C = f(V_{BE})$

$V_{CE} = 10 \text{ V}$



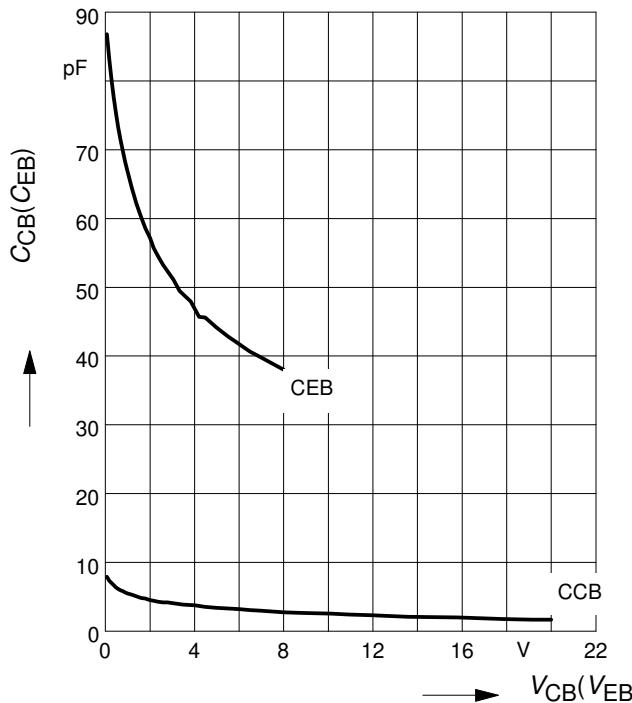
**Transition frequency**  $f_T = f(I_C)$

$V_{CE} = 10 \text{ V}, f = 100 \text{ MHz}$

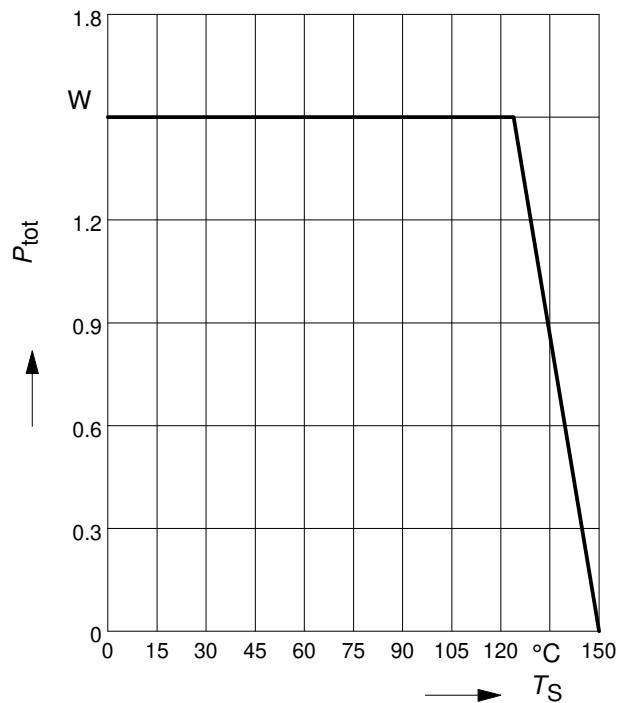


**Collector-base capacitance**  $C_{cb} = f(V_{CB})$

**Emitter-base capacitance**  $C_{eb} = f(V_{EB})$

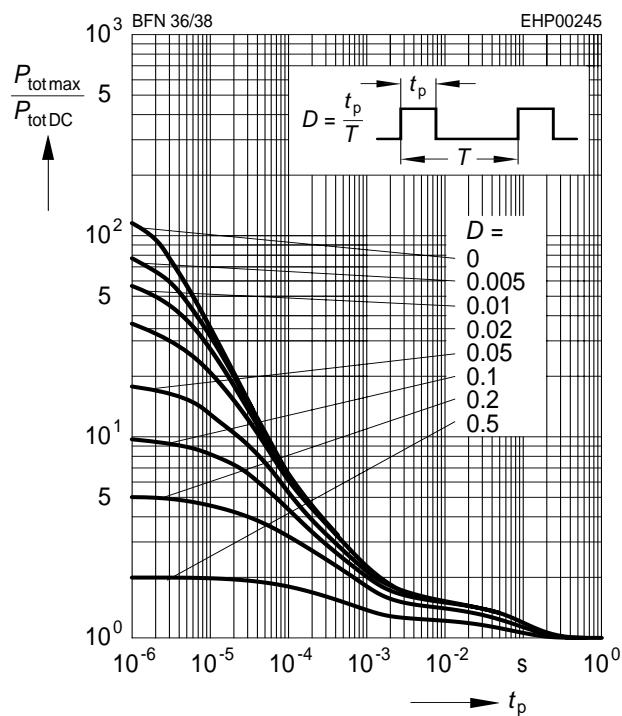


**Total power dissipation**  $P_{tot} = f(T_S)$

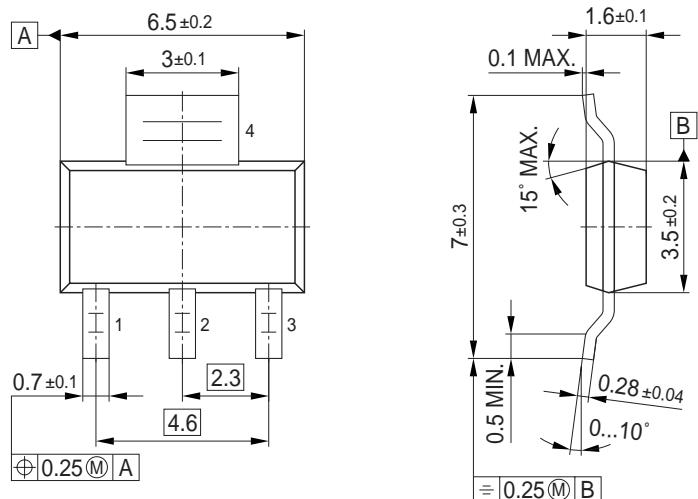


### Permissible Pulse Load

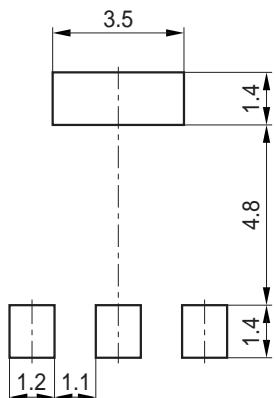
$$P_{totmax}/P_{totDC} = f(t_p)$$



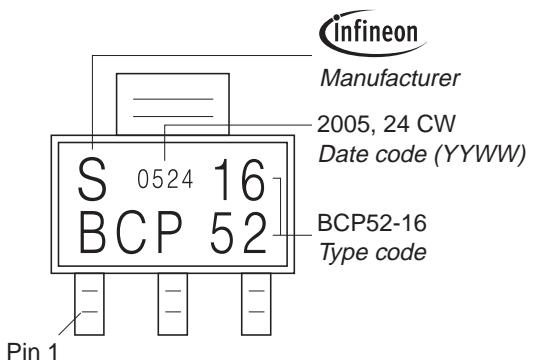
## Package Outline



## Foot Print

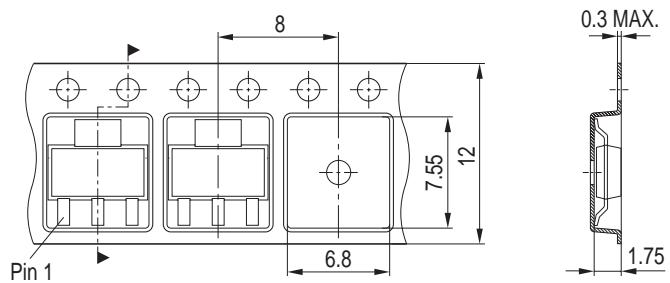


## Marking Layout (Example)



## Packing

Reel ø180 mm = 1.000 Pieces/Reel  
 Reel ø330 mm = 4.000 Pieces/Reel



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